



東莞市威慶電子有限公司

DONGGUAN WEIQING ELECTRONIC CO., LTD

SPEC NO.:2021121301

REV:B

承認書

SPECIFICATION

客戶名稱(CUSTOMER) : 深圳立创电子商务有限公司

產品名稱(PRODUCT NAME) : MMKP82

承認規格(APPROVE ITEM) : 333J/630V P=15MM L=15MM

威慶料號(WEIQING PART NO.) : C382J333JD2L150A40

樣品印字(SAMPLE PRINT) : WQC/ MMKP82 333J/630V

威慶確認表

WEIQING CONFIRM LIST

APPROVED	CHECKED	PREPARED
BASE	徐进阔	何湘华

客戶承認結果

CUSTOMER ACKNOWLEDGE THE RESULT

地址：中國東莞松山湖高新技術產業開發區科技十路7號12棟

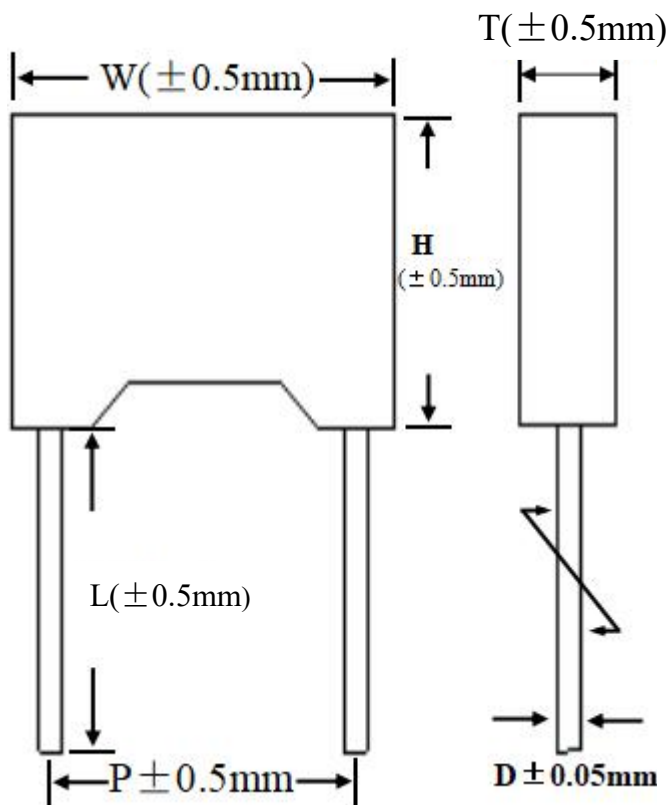
Add: Buiding 12.No.Tenth Road of Science&Technolgy,DongGuan SongShanLake High-tech Industrial Development Zone China

TEL : 0769- 88956188/88956198 FAX : 0769- 88956168

No	Test items	Performance	Test Method
1-1	Withstand voltage (Between Terminals)	Shall be no abnormality	150% Of Rated Voltage, 60sec.
	Between terminal and Enclosure	Shall be no abnormality	UR×200%+1000VDC, 60sec.
1-2	Insulation resistance (Between Terminals)	$IR \geq 15,000M\Omega$	Measured at $100 \pm 15VDC$, For 60sec / 25℃
1-3	Capacitance	Within the tolerance specified	1KHz, 1Vrms Max. at 25℃
1-4	Dissipation Factor	0.001 (0.1%) Max.	1KHz, 1Vrms Max. at 25℃
1-5	Tense Strength of Terminal	No wire breakage and No Damage of Capacitor	1. Load Force : 1.0 Kg 2. Holding Time : 10 ± 1sec
1-6	Bending Strength of Terminal	No wire breakage and No Damage of Capacitor	1. Load Force : 0.5 Kg 2. Bending Time : 4 x 90° in 5sec
1-7	Solder-ability	1. Appearance : No Visible Damage 2. Covering an area of > solder 95%	Soldering Peocess 1.Capacitor preheating temperature of $T < 120^{\circ}C$ 2.Preheating time capacitor $t < 5$ min Single wave soldering 1.Solder temperature: $270 \pm 5^{\circ}C$ 2.Solder time: 2 ± 0.5 sec
1-8	Heat Shock test	(1) Appearance : No Visible Damage (2) Withstand Voltage : Normal (3) Capacitance Change : $\leq \pm 3\%$ of The Initial Value	The terminal of capacitor shall be immersed in the melting solder. a. Solder temperature: $270 \pm 5^{\circ}C$ b. Solder time: 3 ± 0.5 sec c. Test Voltage: 100% of The Rate Voltage For 1min.

No	Test items	Performance	Test Method
1-9	Cold Resistance	(1) Appearance : No Visible Damage (2) Capacitance Change : $\leq 0 \sim -10\%$ of The Initial Value	a. Test Temperature: -40°C b. Test Times: 2Hrs
1-10	Dry Heat Resistance	(1) Appearance : No Visible Damage (2) Withstand Voltage : Normal (3) Capacitance Change : $\leq +5 \sim -2\%$ Of The Initial Value	a. TEST TEMPERATURE: $105^{\circ}\text{C} \pm 2^{\circ}\text{C}$ b. Test Times: 2Hrs
1-11	Humidity Resistance	(1) Appearance : No Visible Damage (2) Withstand Voltage : Normal (3) Capacitance Change : $\leq \pm 10\%$ of The Initial Value (4) Insulation Resistance: $\geq 50\%$ of the rated value (5) DF ($\tan \delta$) ≤ 0.001	a. TEST TEMPERATURE: $40^{\circ}\text{C} \pm 2^{\circ}\text{C}$ b. RELATIVE HUMIDITY: $90 \sim 95\%$ c. Test Times: 240 ± 8 HRS d. TEST VOLTAGE: 125% of The Rated Voltage for 1 min.
1-12	Heat Resistance (Charge & Discharge)	(1) Appearance : No Visible Damage (2) DF ($\tan \delta$) ≤ 0.001 (3) Capacitance Change : $\pm 10\%$ of The Initial Value (4) Insulation Resistance: $\geq 50\%$ of the rated value	a. Test Voltage : Rated Voltage Charge for 2sec. Discharge for 2 sec. Repeated For 1000 ± 100 cycles b. Test Temperature: $85^{\circ}\text{C} \pm 2^{\circ}\text{C}$
1-13	Heat Resistance (Continuous)	(1) Appearance : No Visible Damage (2) DF ($\tan \delta$) ≤ 0.001 (3) Capacitance Change : $\pm 10\%$ of The Initial Value (4) Insulation Resistance: $\geq 50\%$ of the rated value	a. Test Temperature: $85^{\circ}\text{C} \pm 2^{\circ}\text{C}$ b. Test Times: 500 ± 24 Hrs c. TEST VOLTAGE: 125% of The Rated Voltage

2. Dimensions:



CAPACITOR BODY SIZE (Unit:mm)								
CAP	RV	BOX TYP E	W ± 0.5	H ± 0.5	T ± 0.5	D ± 0.05	L ± 0.5	P ± 0.5
333 J	630 V	D2	18	12	6	0.8	15	15

Lead Style

L		H	K	N	M	T	S
						TAPING (refer to next page)	Customer Require
CAP	RV	Lead Style	L model-A section($\pm 0.5\text{mm}$) H.K.N.M model-A section ($\pm 0.5\text{mm}$)		K.N.M model-B section ($\pm 0.5\text{mm}$)		
333J	630V	L	15mm				15mm

3.單峰波峰焊

参照标准: IEC-60384-14

SINGLE WAVE SOLDERING CONDITIONS

組件: 薄膜電容器

Component: Film Capacitors

1. 焊接的建议 Soldering Suggestion:

當焊接電容器時, 焊錫熱會通過導線端子高溫和封裝層傳遞到電容器素子, 因此必須注意高溫和長時間焊接引起的電容器特性衰減或損壞, 請確認焊錫在以下溫度範圍內。

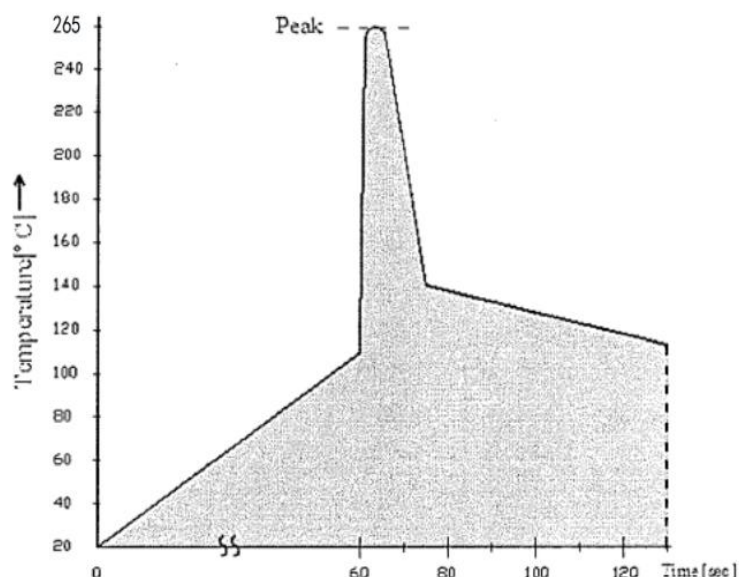
When solder a capacitor, heat in soldering is conducted to the element of the capacitor from wire lead and an enclosure, and hence it should be noted that soldering under high temperature and a long period may cause deterioration of breakdown of capacitors. Be sure to solder within the following temperature condition range.

2. 推荐环境条件 Recommendable Condition:

a. 最高预热温度: $\leq 110^{\circ}\text{C}$ Preheating max temperature: $\leq 110^{\circ}\text{C}$ b. 最大预热时间: ≤ 60 秒Preheating max time: $\leq 60\text{sec}$.c. 温度: $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ Temperature: $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$

d.

温度曲线项目	SnPb 合金	无铅合金 (SAC、SbCu 合金)
驻留时间 (板厚在 1.5mm~2.25mm[0.060in~0.090in])	2s~4s	3s~5s
驻留时间 (板厚 > 2.25mm[0.090in])	4s~8s	5s~10s



3. 手工焊接 Hand Soldering:

a. 烙铁最高温度 Soldering iron top temperature: $\leq 350^{\circ}\text{C}$ 焊接时间 Soldering tim: $\leq 3\text{sec}$.

4. 如果需要焊接两次, 第二次焊接必须等到电容器恢复到常温。建议时间 24 小时。

If re-work or dipping twice is necessary, it should be done after the capacitor returned to the normal temperature. Suggestion time is 24 hours.

5. 回流焊接 Reflow Solder

不适合回流焊接 Not suitable for reflow soldering.

4: 雙峰波峰焊

参照标准: IEC-60384-14

DOUBLE WAVE SOLDERING CONDITIONS

組件: 薄膜電容器

Component: Film Capacitors

1. 焊接的建议 Soldering Suggestion:

當焊接電容器時, 焊锡热会通过导线端子高温和封装层传递到電容器素子, 因此必须注意高温和长时间焊接引起的电容器特性衰减或损坏, 请确认焊锡在以下温度范围内。

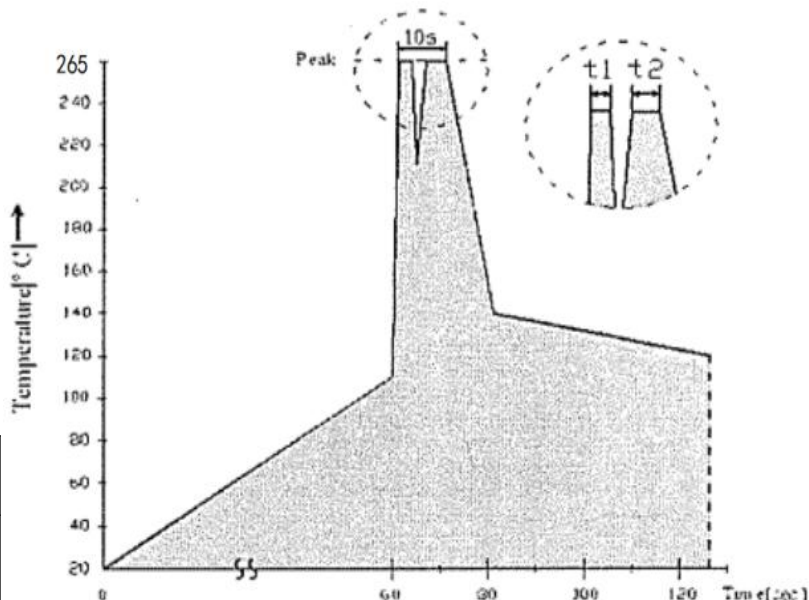
When solder a capacitor, heat in soldering is conducted to the element of the capacitor from wire lead and an enclosure, and hence it should be noted that soldering under high temperature and a long period may cause deterioration of breakdown of capacitors. Be sure to solder within the following temperature condition range.

2. 推荐环境条件 Recommendable Condition:

a. 最高预热温度: $\leq 110^{\circ}\text{C}$ Preheating max temperature: $\leq 110^{\circ}\text{C}$ b. 最大预热时间: ≤ 60 秒Preheating max time: $\leq 60\text{sec.}$ c. 温度: $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ Temperature: $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$

d.

温度曲线项目	SnPb 合金 (T1+T2)	无铅合金 (SAC 、SbCu 合金)
驻留时间 (板厚在 1.5mm~2.25mm[0.060in ~0.090in])	2s~4s	3s~5s
驻留时间 (板厚 > 2.25mm[0.090in])	4s~8s	5s~10s



3. 手工焊接 Hand Soldering:

b. 烙铁最高温度 Soldering iron top temperature: $\leq 350^{\circ}\text{C}$ c. 焊接时间 Soldering time: $\leq 3\text{sec.}$

4. 如果需要焊接两次, 第二次焊接必须等到电容器恢复到常温。建议时间 24 小时。

If re-work or dipping twice is necessary, it should be done after the capacitor returned to the normal temperature. Suggestion time is 24 hours.

5. 回流焊接 Reflow Solder

不适合回流焊接 Not suitable for reflow soldering.

5. 频率和温度曲线图 Frequency and temperature curves:

说明: MMKP82 系列谐振电容原材料属于聚丙烯: PP 类材料, 对应相应的材料线条走向即可

